

Part Number : [755860104](#)

Product Description : 0.80mm Pitch, iPass I/O Surface Mount Receptacle, Right-Angle, External Application, 38 Circuit, 0.76µm Gold (Au), Solder Ring

Series Number : 75586

Status : Not Recommended For New Design

Product Category : High-Speed I/O Connectors

Documents and Resources

Drawings

[755860104 sd.pdf](#)

[PK-75586-002-001.pdf](#)

[PK-75586-101-001.pdf](#)

3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

[Symbol and Footprint \(Multi-Format\)](#)

[EE-75586-001-001.pdf](#)

[SI-75586-0001-001.pdf](#)

[SP-75586-001-001.zip](#)

Specifications


[AS-170432-0003-001.pdf](#)

[AS-75586-001-001.pdf](#)

[PS-75586-001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant

Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Not Recommended For New Design
Category	High-Speed I/O Connectors
Series	75586
Description	0.80mm Pitch, iPass I/O Surface Mount Receptacle, Right-Angle, External Application, 38 Circuit, 0.76µm Gold (Au), Solder Ring
Application	Wire-to-Board
Component Type	Receptacle
Product Name	iPass,Mini Multi-Lane,PCI Express
Type	Pluggable
UPC	800756909219

Agency

CSA	LR19980
-----	---------

UL	E29179
----	--------

Electrical

Current - Maximum per Contact	0.5A
Data Rate	10.0 Gbps
Grounding to Panel	N/A
Shielded	No
Voltage - Maximum	30V AC (RMS)/DC

Physical

Boot Color	N/A
Circuits (Loaded)	38
Circuits (maximum)	38
Color - Resin	Black
Durability (mating cycles max)	250
Flammability	94V-0
Gender	Female
Keying to Mating Part	No
Lock to Mating Part	No
Material - Metal	Copper-Nickel-Zinc, High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	0.991/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Embossed Tape on Reel
Panel Mount	No
PCB Locator	Yes
PCB Retention	No
PCB Thickness - Recommended	1.35mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm

Plating min - Termination	2.540µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1
Temperature Range - Operating	-40° to +80°C
Termination Interface Style	Surface Mount
Waterproof / Dustproof	No
Wire Insulation Diameter	N/A
Wire Size (AWG)	N/A

Solder Process Data

Max-Duration	20
Lead-Free Process Capability	REFLOW
Max-Cycle	1
Max-Temp	260

Mates With / Use With

Use with Part(s)

Description	Part Number
External iPass Mini Multi-Lane SAS Guide Frames	<u>74548</u>

This document was generated on May 09, 2026